January 25, 2001, with No. 09/083,057 having originally been filed May 22, 1998, the contents of No. 09/083,057 being incorporated herein by reference in their entirety.--

Please delete the paragraph on page 4, lines 9-21, and substitute therefor the following new paragraph:

--The first invention relates to a process for preparing a phosphor pattern for a field emission display panel which comprises the steps of: (I) forming (A) a photosensitive resin composition layer containing a phosphor on a substrate to which a conductive layer is formed; (II) selectively irradiating active light to (A) the photosensitive resin composition layer containing a phosphor ~~imagewisely~~; (III) selectively removing (A) the photosensitive resin composition layer containing a phosphor to which active light has been ~~imagewisely~~ selectively irradiated by development to form a pattern; and (IV) calcining the pattern to remove unnecessary portion to form a phosphor pattern.--

Please delete the paragraph on page 6, lines 31-35, and substitute therefor the following new paragraph:

--The ninth invention relates to a photosensitive element for a field emission display panel, wherein said element has (B) a filling layer on a support film, and (A) a photosensitive resin composition layer containing a phosphor on (B) ~~he~~ the filling layer.--

Please delete the paragraph on page 7, lines 30-33, and substitute therefor the following new paragraph:

--~~Fig. 3 is a~~ Figs. 3(I)-3(VII) are schematic ~~view~~ views showing one example of respective steps in a process for preparing a phosphor pattern for a field emission display panel of the present invention.--

Please delete the paragraph on page 8, lines 1-3, and substitute therefor the following new paragraph:

--~~Fig. 4 is a~~ Figs. 4(I)-4(VI) are schematic ~~view~~ views showing one example of a step for forming a multi-colored pattern of the present invention.--

Please delete the paragraph on page 8, lines 19-30, and substitute therefor the following new paragraph:

--The first invention relates to a process for preparing a phosphor pattern for a field emission display panel which comprises the steps of: (I) forming (A) a photosensitive resin composition layer containing a phosphor on a substrate to which a conductive layer is formed; (II) selectively irradiating active light to (A) the photosensitive resin composition layer containing a phosphor ~~imagewisely~~; (III) selectively removing (A) the photosensitive resin composition layer containing a phosphor to which active light has been ~~imagewisely~~ selectively irradiated by

development to form a pattern; and (IV) calcining the pattern to remove unnecessary portion to form a phosphor pattern.--

Please delete the paragraphs on page 17, lines 7-32, and substitute therefor the following new paragraphs:

--As sensitivity of (A) the photosensitive resin composition layer containing a phosphor of the present invention, when active light is ~~imagewisely~~ selectively irradiated with a predetermined dose of active light by using 21 grades step tablet (available from Hitachi Chemical Co., Ltd.), etc. in the step of ~~imagewisely~~ selectively irradiating active light mentioned hereinbelow, and development is carried out by the step of removing unnecessary portion by development mentioned hereinbelow, the step number of the remaining step tablet of (A) the photosensitive resin composition layer containing a phosphor is preferably 1 to 21 grades, more preferably 1.5 to 18 grades, particularly preferably 2 to 15 grades.

As resolution of (A) the photosensitive resin composition layer containing a phosphor of the present invention, when active light is ~~imagewisely~~ selectively irradiated with a predetermined dose of active light by using a photomask for evaluating resolution (available from Hitachi Chemical Co., Ltd.), etc., and development is carried out by the step of removing unnecessary portion by development mentioned hereinbelow, the minimum line/space of the remaining (A) the photosensitive resin composition layer containing a phosphor is preferably 1 mm/ 1 mm or less, more preferably 900 μm/900 μm or less, particularly preferably 800 μm/800 μm or less.--

Please delete the paragraph bridging pages 17 and 18, and substitute therefor the following new paragraph:

--As adhesive properties of (A) the photosensitive resin composition layer containing a phosphor of the present invention, when active light is ~~imagewisely~~ selectively irradiated with a predetermined dose of active light by using a photomask for evaluating ~~resolution~~ adhesiveness (available from Hitachi Chemical Co., Ltd.), etc., and development is carried out by the step of removing unnecessary portion by development mentioned hereinbelow, the minimum line/space of the remaining (A) the photosensitive resin composition layer containing a phosphor is preferably 400 μm/400 μm or less, more preferably 300 μm/400 μm or less, particularly preferably 350 μm/400 μm or less.--

Please delete the paragraph on page 23, lines 5-14, and substitute therefor the following new paragraph:

--In the following, one example of the process for preparing a phosphor pattern for a field emission display panel of the present invention will be explained by referring to the respective steps of ~~Fig. 3~~ Figs. 3(I)-3(VII) when a substrate for preparing a phosphor layer to be used as a transmittance type FED front panel to which a conductive layer and a black matrix are formed. Incidentally, ~~Fig. 3 is a~~ Figs. 3(I)-3(VII) are schematic ~~view~~ views showing respective steps of one example of the process for preparing a phosphor pattern for a field emission display panel of the present

invention.--

Please delete the paragraphs on page 30, lines 9-29, and substitute therefor the following new paragraphs:

--(II) Step of irradiating active light ~~imagewisely~~ selectively to (A) photosensitive resin composition layer containing a phosphor

The state of ~~imagewisely~~ selectively irradiating active light to (A) the photosensitive resin composition layer 4 containing a phosphor is shown in Fig. 3(V). In Fig. 3(V), the reference numeral 7 is a photomask and 8 is active light.

In Fig. 3(V), as the method of ~~imagewisely~~ selectively irradiating active light 8, there may be mentioned a method in which active light 8 is ~~imagewisely~~ selectively irradiated to the upper portion of (A) the photosensitive resin composition layer 4 containing a phosphor in the state of Fig. 3(IV) through a photomask 7 such as a negative film, a positive film, etc., and the like.

At this time, on (A) the photosensitive resin composition layer 4 containing a phosphor, the above-mentioned support film is newly covered and active light 8 may be ~~imagewisely~~ selectively irradiated.--

Please delete the paragraph on page 31, lines 29-32, and substitute therefor the following new paragraph:

--(III) Step of forming pattern by selectively removing (A) the photosensitive resin composition layer containing a phosphor to which active light is ~~imagewisely~~ selectively irradiated by development.--

Please delete the paragraphs on page 32, lines 3-21, and substitute therefor the following new paragraphs:

--In Fig. 3(VI), as the method of development, for example, when the support film and (B) the filling layer 5 are present on (A) the photosensitive resin composition layer 4 containing a phosphor after ~~imagewisely~~ selectively irradiating the active light 8, there may be mentioned a method in which, after removing these layers, development is carried out by the conventionally known method such as spraying, dipping under rocking, brushing, scrapping, etc. by using a known developer such as an alkali aqueous solution, an aqueous developer, an organic solvent, etc., to remove the unnecessary portion.

As the method of removing the unnecessary portion of (A) the photosensitive resin composition layer 4 containing a phosphor, dry development in which by utilizing the difference in adhesive properties between the exposed portion and the unexposed portion, only the unnecessary portion having adhesiveness of (A) the photosensitive resin composition layer 4 containing a phosphor is peeled off may be carried out.--

Please delete the paragraph on page 33, lines 22-36, and substitute therefor the following new paragraph:

--In the aqueous developer comprising water and at least one kind of an organic solvent (when the organic solvent is not dissolved in water, it is an emulsion solution), as the organic solvent, there may be mentioned, for example, acetone alcohol, acetone, ethyl acetate, alkoxyethanol having an alkoxy group with 1 to 4 carbon atoms, ethyl alcohol, isopropyl alcohol, butyl alcohol, diethylene glycol monomethyl ether, diethylene glycol monoethyl ether, diethylene glycol monobutyl ether, triethylene glycol monobutyl ether, dipropylene glycol monomethyl ether, dipropylene glycol monopropyl ether, 3-methyl-3-methoxybutyl acetate, 1,1,1-trichloroethane, N-methyl-pyrrolidone, N,N-dimethylformamide, cyclohexanone, methyl isobutyl ketone, ~~g-butyrolactone~~ γ-butyrolactone, etc. These may be used singly or in combination of two or more.--

Please delete the paragraph bridging pages 36 and 37, and substitute therefor the following new paragraph:

--In ~~Fig. 4~~ Figs. 4(I)-4(VI), the state in which a multi-colored pattern containing the photosensitive resin composition layer containing a phosphor which forms colors of red, green and blue is formed by repeating the respective steps of (I) to (III) for each color is shown. In ~~Fig. 4~~ Figs. 4(I)-4(VI), the reference numeral 4'a is a first color pattern, 4'b is a second color pattern, and 4'c is a third color pattern.--

Please delete the paragraphs on page 50, lines 11-23, and substitute therefor the following new paragraphs:

--(II) Step of irradiating active light to (A) the photosensitive resin composition layer containing a phosphor ~~imagewisely~~ selectively

Then, onto (A) the photosensitive resin composition layer containing a phosphor, a photomask for test was closely contacted and active light was ~~imagewisely~~ selectively irradiated with 500 mJ/cm^2 by using HMW-590 type exposure machine (trade name, available from ORC Seisakusho).

(III) Step of selectively removing (A) the photosensitive resin composition layer containing a phosphor to which active light was ~~imagewisely~~ selectively irradiated by development.--

Please delete the paragraphs on page 51, lines 15-27, and substitute therefor the following new paragraphs:

--(II) Step of irradiating active light to (A) the photosensitive resin composition layer containing a phosphor ~~imagewisely~~ selectively

Then, onto (A) the photosensitive resin composition layer containing a phosphor, a photomask for test was closely contacted and active light was ~~imagewisely~~ selectively irradiated with 500 mJ/cm^2 by using HMW-590 type exposure machine (trade name, available from ORC Seisakusho).

(III) Step of selectively removing (A) the photosensitive resin composition layer containing a phosphor to which active light was ~~imagewisely~~ selectively irradiated by development.--

Please delete the paragraphs on page 52, lines 19-31, and substitute therefor the following new paragraphs:

--(II) Step of irradiating active light to (A) the photosensitive resin composition layer containing a phosphor ~~imagewisely~~ selectively

Then, onto (A) the photosensitive resin composition layer containing a phosphor, a photomask for test was closely contacted and active light was ~~imagewisely~~ selectively irradiated with 500 mJ/cm^2 by using HMW-590 type exposure machine (trade name, available from ORC Seisakusho).

(III) Step of selectively removing (A) the photosensitive resin composition layer containing a phosphor to which active light was ~~imagewisely~~ selectively irradiated by development.--